**Product data sheet** 

### 1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small DFN1006D-2 (SOD882D) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

### 2. Features and benefits

- Average forward current: I<sub>F(AV)</sub> ≤ 1 A
- Reverse voltage: V<sub>R</sub> ≤ 20 V
- Low forward voltage V<sub>F</sub> ≤ 490 mV
- · Ultra small and leadless SMD plastic package
- Solderable side pads
- Package height typ. 0.37 mm

### 3. Applications

- Low voltage rectification
- · High efficiency DC-to-DC conversion
- Switch mode power supply
- · Reverse polarity protection
- · Low power consumption applications
- · Ultra high-speed switching
- · LED backlight for mobile application

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> $\leq$ 130 °C	-	-	1	Α
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C	-	-	20	V
V <sub>F</sub>	forward voltage	$I_F$ = 1 A; $t_p \le 300$ μs; $\delta \le 0.02$ ; pulsed; $T_j$ = 25 °C	-	428	490	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 20 V; T <sub>j</sub> = 25 °C	-	87	200	μΑ



# 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]		
2	Α	anode		K <b>-}</b> A
			Transparent top view	sym001
			DFN1006D-2 (SOD882D)	

<sup>[1]</sup> The marking bar indicates the cathode.

# 6. Ordering information

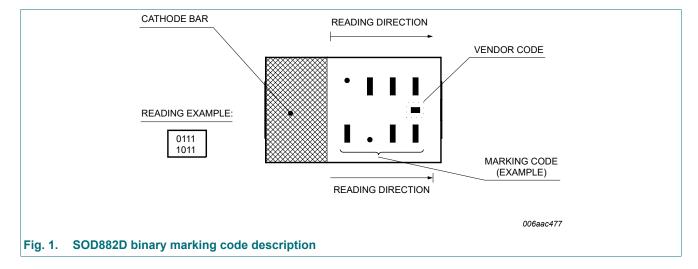
**Table 3. Ordering information** 

Type number	Package		
	Name	Description	Version
PMEG2010BELD		leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.65 mm pitch; 1 mm x 0.6 mm x 0.4 mm body	SOD882D

# 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PMEG2010BELD	0000
	1001



## 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>R</sub>	reverse voltage	T <sub>j</sub> = 25 °C		-	20	V
I <sub>F</sub>	forward current	T <sub>sp</sub> ≤ 130 °C		-	1	А
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; $T_{sp} \le$ 130 °C		-	1	А
		$\delta$ = 0.5; f = 20 kHz; square wave; $T_{amb} \le$ 80 °C	[1]	-	1	А
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1 \text{ ms}; \delta \le 0.25$		-	3	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 8 ms; square wave; $T_{j(init)}$ = 25 °C		-	6	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[2] [3]	-	370	mW
			[4] [3]	-	735	mW
			[1] [3]	-	1135	mW
Tj	junction temperature			-	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C

- [1] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Reflow soldering is the only recommended soldering method.
- [4] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	[:	[1] [2] [3]	-	-	340	K/W
			[1] [4] [3]	-	-	170	K/W
			[1] [5] [3]	-	-	110	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		[6]	-	-	25	K/W

<sup>[1]</sup> For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.

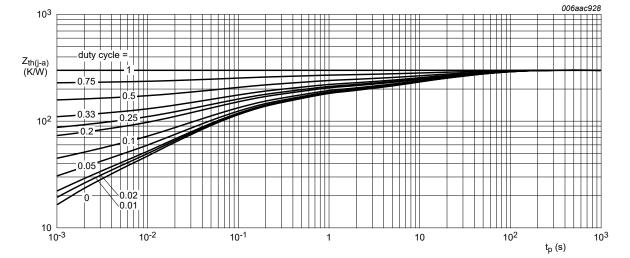
<sup>[2]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

<sup>[3]</sup> Reflow soldering is the only recommended soldering method.

<sup>[4]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

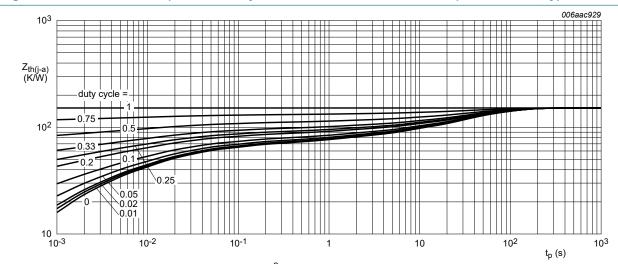
<sup>[5]</sup> Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

<sup>[6]</sup> Soldering point of cathode tab.



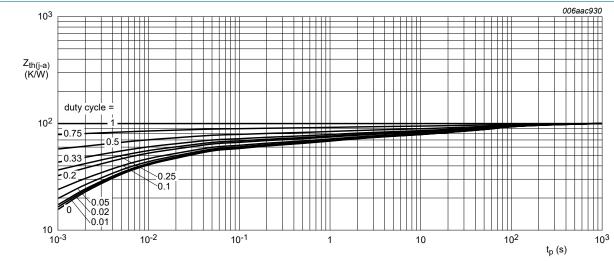
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>F</sub>	forward voltage	$I_F$ = 100 mA; $t_p \le 300$ μs; $δ \le 0.02$ ; pulsed; $T_j$ = 25 °C	-	266	310	mV
		$I_F$ = 500 mA; $t_p \le 300$ μs; $δ \le 0.02$ ; pulsed; $T_j$ = 25 °C	-	353	390	mV
		$I_F$ = 1 A; $t_p \le 300 \ \mu s$ ; $\delta \le 0.02$ ; pulsed; $T_j$ = 25 °C	-	428	490	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C	-	28	50	μΑ
		V <sub>R</sub> = 20 V; T <sub>j</sub> = 25 °C	-	87	200	μΑ
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	31	40	pF
t <sub>rr</sub>	reverse recovery time	$I_F = 0.5 \text{ A}$ ; $I_R = 0.5 \text{ A}$ ; $I_{R(meas)} = 0.1 \text{ A}$ ; $I_{j} = 25 \text{ °C}$	-	1.6	-	ns
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$	-	565	-	mV

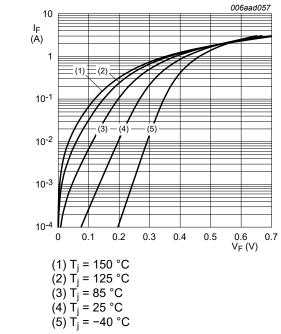


Fig. 5. Forward current as a function of forward voltage; typical values

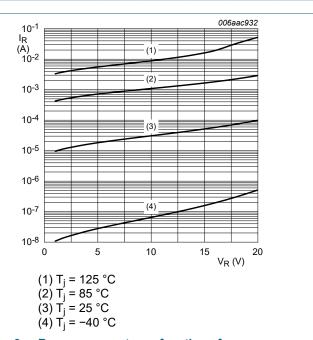


Fig. 6. Reverse current as a function of reverse voltage; typical values

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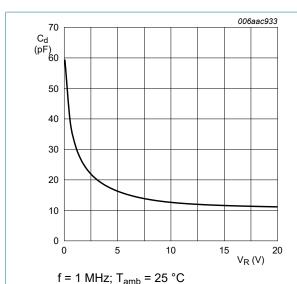
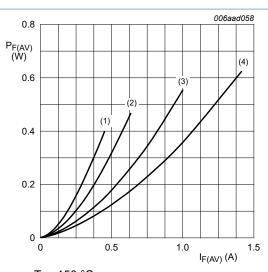
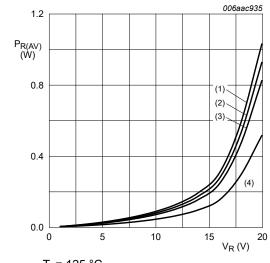


Fig. 7. Diode capacitance as a function of reverse voltage; typical values



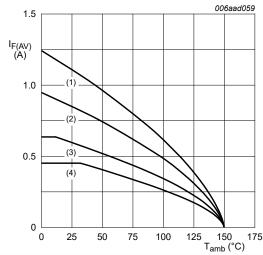
 $T_j = 150 \,^{\circ}\text{C}$ (1)  $\delta = 0.1$ (2)  $\delta = 0.2$ (3)  $\delta = 0.5$ (4)  $\delta = 1$ 

Fig. 8. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 125 \,^{\circ}\text{C}$ (1)  $\delta = 1 \,(\text{DC})$ (2)  $\delta = 0.9$ ;  $f = 20 \,\text{kHz}$ (3)  $\delta = 0.8$ ;  $f = 20 \,\text{kHz}$ (4)  $\delta = 0.5$ ;  $f = 20 \,\text{kHz}$ 

Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

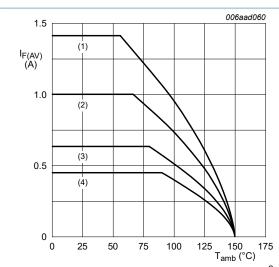
 $T_j = 150 \, ^{\circ}\text{C}$ 

 $(1) \delta = 1$ (2)  $\delta = 0.5$ 

 $(3) \delta = 0.2$ 

 $(4) \delta = 0.1$ 

Fig. 10. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1  $\mbox{cm}^2$ 

 $T_i = 150 \,{}^{\circ}\text{C}$ 

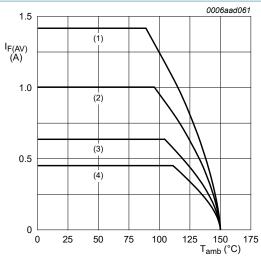
 $(1) \delta = 1$ 

 $(2) \delta = 0.5$ 

 $(3) \delta = 0.2$ 

 $(4) \delta = 0.1$ 

Fig. 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

 $T_i = 150 \,{}^{\circ}\text{C}$ 

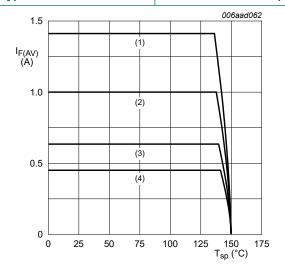
 $(1) \delta = 1$ 

 $(2) \delta = 0.5$ 

 $(3) \delta = 0.2$ 

 $(4) \delta = 0.1$ 

Fig. 12. Average forward current as a function of ambient temperature; typical values



T<sub>i</sub> = 150 °C

 $(1) \delta = 1$ 

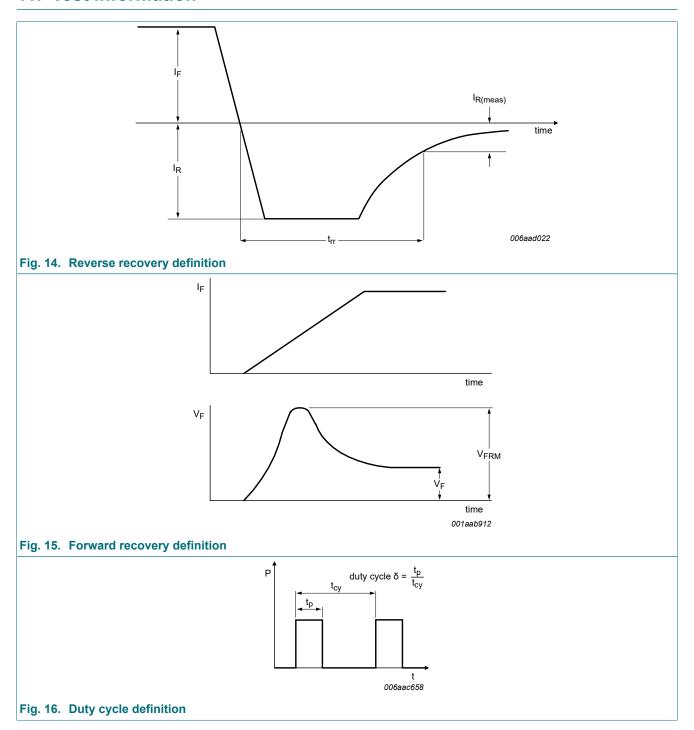
 $(2) \delta = 0.5$ 

 $(3) \delta = 0.2$ 

 $(4) \delta = 0.1$ 

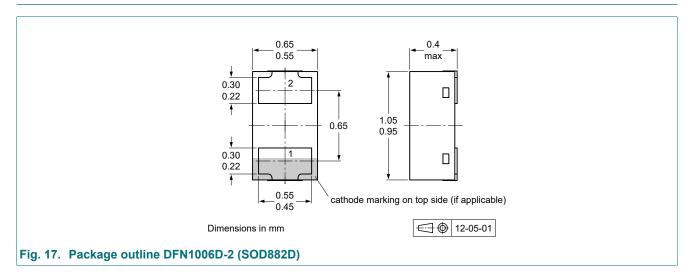
Fig. 13. Average forward current as a function of solder point temperature; typical values

## 11. Test information

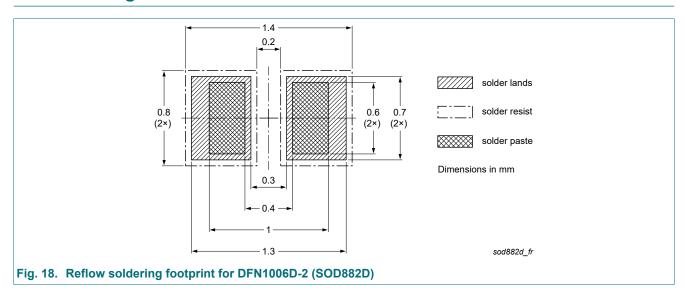


The current ratings for the typical waveforms are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

# 12. Package outline



# 13. Soldering



# 14. Revision history

#### Table 8. Revision history

Table 6. Revision history								
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes				
PMEG2010BELD v.3	20221102	Product data sheet	-	PMEG2010BELD v.2				
Modifications:	<ul> <li>Product(s) changed to non-automotive qualification. Please refer to nexperia.com for automotive (-Q) product alternative(s).</li> </ul>							
PMEG2010BELD v.2	20150804	Product data sheet	-	PMEG2010BELD v.1				
PMEG2010BELD v.1	20120418	Product data sheet	-	-				

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#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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